Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP HSR6804 Router Chassis (JG362A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2 #

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on mounting angle 2, and then remove mounting angle 2 from the chassis.
2. Remove film 3 from plastic panel 4.
3. Remove plastic panel 4 from the chassis.
4. Unscrew the screws on front panel 5, and then remove front panel 5 from the chassis.
5. Unscrew the screws on blank filler panel 6, and then remove blank filler panel 6 from the chassis.
6. Unscrew the screws on front panel 7, and then remove front panel 7 from the chassis.
7. Unscrew the screws on blank filler panel 8, and then remove blank filler panel 8 from the chassis.
8. Unscrew the screws on power module 9, and then remove power module 9 from the chassis.
9. Unscrew the screws on blank power module panel 10, and then remove blank power module panel 10 from the chassis.
10. Unscrew the screws on blank poe module panel 11, and then remove blank poe module panel 11 from the chassis.
11. Unscrew the screws on fan frame 12, and then remove fan frame 12 from the chassis.
12. Unscrew the screws on dustproof frame 13, and then remove dustproof frame 13 from the chassis.
13. Unscrew the screws on guide rail 14, and then remove guide rail 14 from the chassis.
14. Unscrew the screws on back cover 15, and then remove back cover 15 from the chassis.
15. Unscrew the screws on PCB 16, and then remove PCB 16 from the chassis.
16. Unscrew the screws on PCB 17, and then remove PCB 17 from the chassis.
17. Remove shielding finger 18 from the chassis.
18. Unscrew the screws on wire channel 2-2, and then remove wire channel 2-2 from mounting angle 2-1.
19. Unscrew the screws on pcb 5-1, sheet metal 5-2 and heat sink 5-7, then remove the pcb 5-1, sheet metal 5-2 and heat sink 5-7 from front panel 5-5.
20. Remove light pipe 5-6 from pcb 5-1.
21. Remove shielding finger 5-3 from front panel 5-5.
22. Remove film 5-4 from front panel 5-5.
23. Remove conductive foamfrom 5-8 from front panel 5-5.
24. Remove shielding finger 6-2 from blank filler panel 6-1.
25. Remove film 6-3 from front panel 6-1.
26. Unscrew the screws on pcb 7-1 and sheet metal 7-2, then remove the pcb 1, sheet metal 7-2 from front panel 7-6.
27. Unscrew the screws on guiding set 7-3, then remove guiding set 7-3 from pcb 7-1.
28. Remove shielding finger 7-4 from front panel 7-6.
29. Remove film 7-5 from front panel 7-6.
30. Remove shielding finger 8-2 from blank filler panel 8-1.
31. Remove film 8-3 from front panel 8-1.
32. Remove shielding finger 10-2 from blank power module panel 10-1.
33. Remove shielding finger 11-2 from blank poe module panel 11-1.
34. Unscrew the screws on pcb 12-1, and then remove pcb 12-1 from fan frame 12-8.
35. Unscrew the screws on Fan Frame Plate 12-2, and then remove Fan Frame Plate 12-2 from fan frame 12-8.
36. Unscrew the screws on fan 12-3, and then remove fan 12-3 from fan frame 12-8.
37. Unscrew the screws on handle 12-4, and then remove handle 12-4 from fan frame 12-8.
38. Unscrew the screws on Fan Plastic Panel 12-5, and then remove Fan Plastic Panel 12-5 from fan frame 12-8.
39. Remove shielding finger 12-6 from fan frame 12-8.
40. Remove film 12-7 from fan frame 12-8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

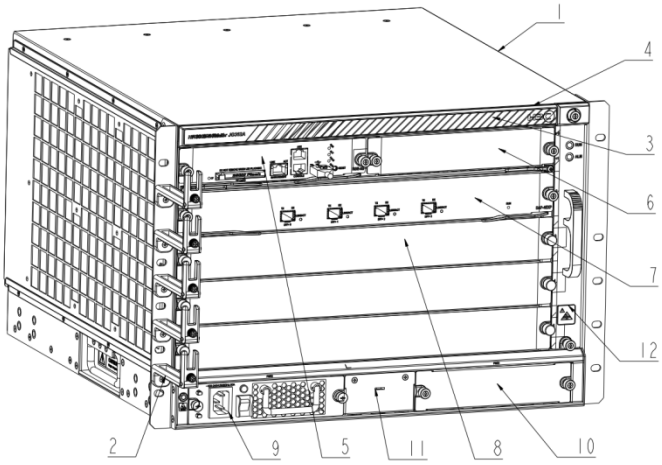

Figure 1 Treatments to the product（front view）

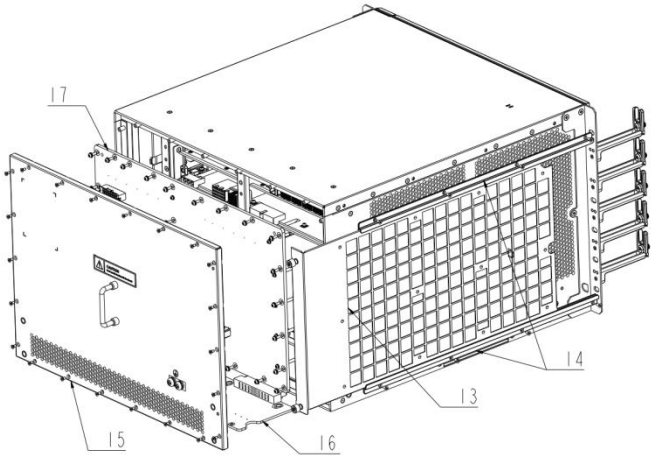

Figure 2 Treatments to the product(rear view)

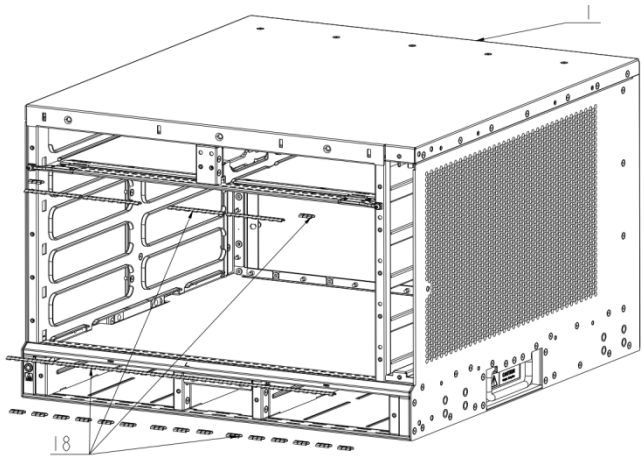

Figure 3 Part 1

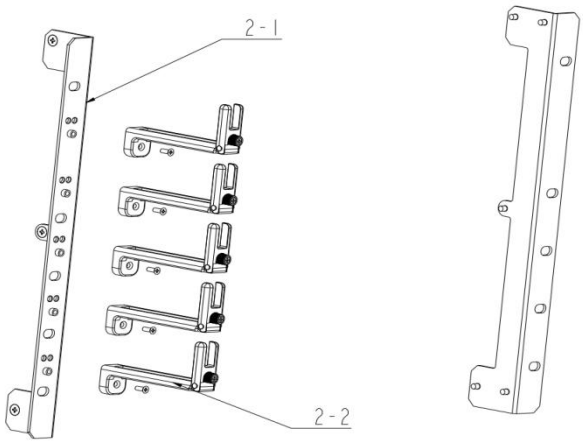

Figure 4 Treatments to mounting angle 2

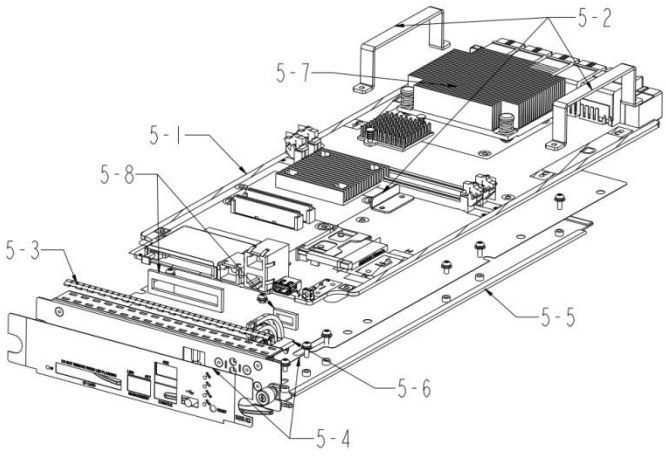

Figure 5 Treatments to front panel 5

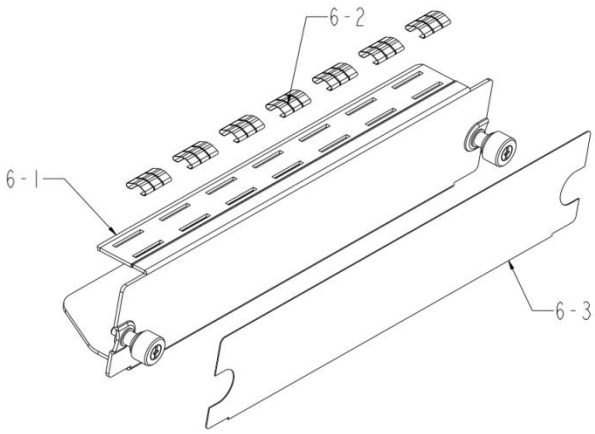

Figure 6 Treatments to blank filler panel 6

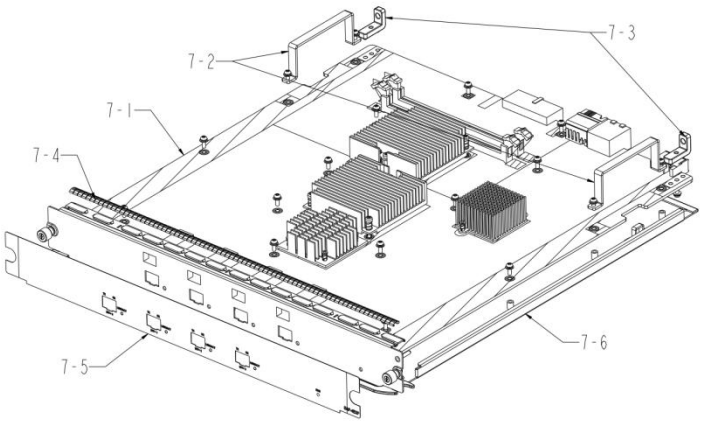

Figure 7 Treatments to front panel 7

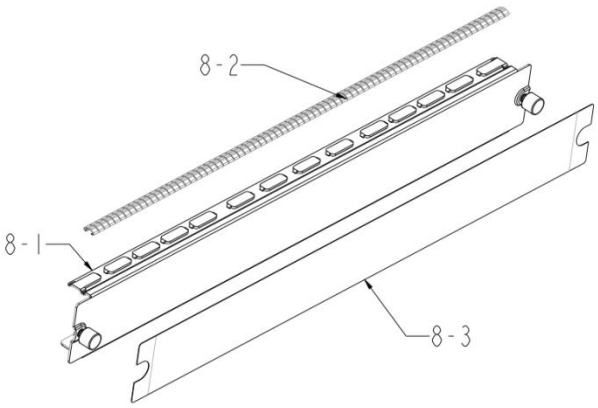

Figure 8 Treatments to blank filler panel 8

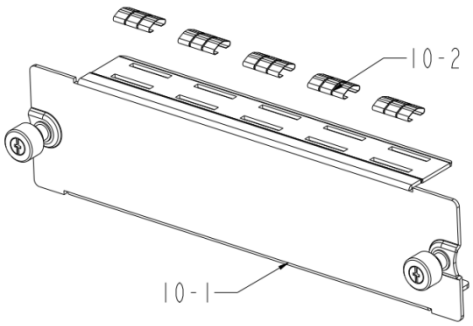

Figure 9 Treatments to blank power module panel 10

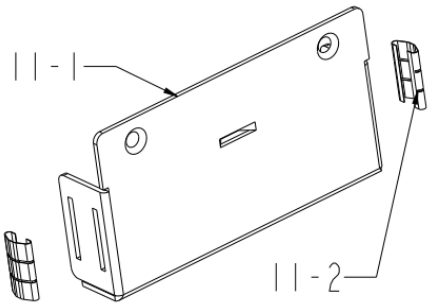

Figure 10 Treatments to blank poe module panel 11

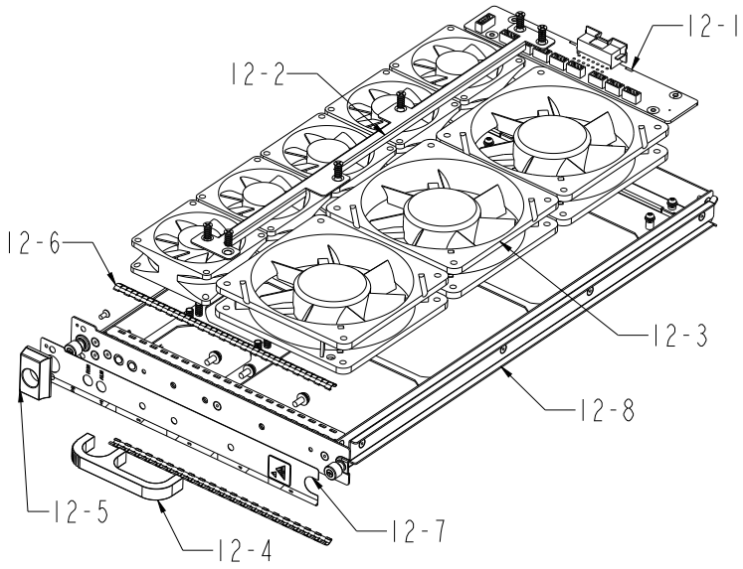

Figure 11 Treatments to fan frame 12

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details

	1	Fe	20826	58.4%		Fe recycling
	2	Fe	594	1.67%		Fe recycling
	3	PC	2	0.006%		Pla recycling
	4	PC	34	0.1%		Pla recycling
5						
	5-1	Complex PWB	815	2.3%	The surface lf PCB is greater than 10 square centimeters	
	5-2	Fe	53	0.15%		Fe recycling
	5-3	Be-Cu	1	0.003%		Cu recycling
	5-4	PC	18	0.05%		Pla recycling
	5-5	Fe	725	2.1%		Fe recycling
	5-6	PC	2	0.006%		Pla recycling
	5-7	AL	186	0.52%		Al recycling
6						
	6-1	Fe	177	0.5%		Fe recycling
	6-2	Be-Cu	1	0.003%		Cu recycling
	6-3	PC	3	0.009%		Pla recycling
7						
	7-1	Complex PWB	1826	5.13%	The surface lf PCB is greater than 10 square centimeters	
	7-2	Fe	38	0.11%		Fe recycling
	7-3	Al	9	0.03%		Al recycling
	7-4	Be-Cu	4	0.012%		Cu recycling
	7-5	PC	6	0.02%		Pla recycling
	7-6	Fe	1817	5.11%		Fe recycling
8						
	8-1	Fe	303	0.85%		Fe recycling
	8-2	Be-Cu	4	0.012%		Cu recycling
	8-3	PC	6	0.02%		Pla recycling
	9		2430	6.83%		
10						
	10-1	Fe	122	0.34%		Fe recycling
	10-2	Be-Cu	1	0.003%		Cu recycling
11						
	11-1	Fe	42	0.12%		Fe recycling
	11-2	Be-Cu	1	0.003%		Cu recycling
12						
	12-1	Complex PWB	121	0.34%	The surface lf PCB is greater than 10 square centimeters	
	12-2	Fe	58	0.17%		Fe recycling
	12-3	Pla	90*5+198*3	2.94%		Pla recycling
	12-4	Al	24	0.07%		Al recycling
	12-5	PC	4	0.012%		Pla recycling
	12-6	Be-Cu	1	0.003%		Cu recycling
	12-7	PC	3	0.009%		Pla recycling
	12-8	Fe	945	2.66%		Fe recycling
	13	Fe	413	1.16%		Fe recycling
	14	Al	88	0.25%		Al recycling
	15	Fe	1122	3.16%		Fe recycling
	16	Complex PWB	400	1.13%	The surface lf PCB is greater than 10 square centimeters	
	17	Complex PWB	1300	3.66%	The surface lf PCB is greater than 10 square	

					centimeters	
	18	Be-Cu	7	0.03%		Cu recycling

4. Revised record

Date	Version	Author	Modify content
2012.10.31	V0	Liu Xiaoyuan	Initial version